

# 74AC11138 3-Line to 8-Line Decoder/Demultiplexer

## 1 Features

- Designed specifically for high-speed memory decoders and data transmission systems
- Incorporates three enable inputs to simplify cascading and/or data reception
- Center-Pin  $V_{CC}$  and GND configurations minimize high-speed switching noise
- EPIC™ (Enhanced-Performance Implanted CMOS) 1- $\mu$ m process
- 500-mA typical latch-up immunity at 125 °C
- Package options include plastic small-outline (D) and thin shrink small-outline (PW) packages, and standard plastic 300-mil DIPs (N)

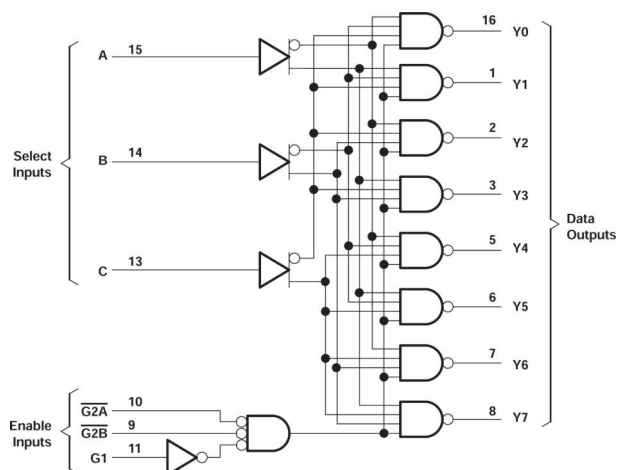
## 2 Description

The 74AC11138 circuit is designed to be used in high-performance memory-decoding or data-routing applications requiring very short propagation delay times.

### Package Information

PART NUMBER	PACKAGE <sup>(1)</sup>	PACKAGE SIZE <sup>(2)</sup>	BODY SIZE (NOM) <sup>(3)</sup>
74AC11138	D (SOIC, 16)	9.9mm × 6mm	9.9mm × 3.9mm
	N (PDIP, 16)	19.3mm × 9.4mm	19.3mm × 6.35mm
	NS (SOP, 16)	10.2mm × 7.8mm	10.3mm × 5.3mm
	PW (TSSOP, 16)	5.00mm × 6.4mm	5.00mm × 4.4mm

- For more information, see [Section 10](#).
- The package size (length × width) is a nominal value and includes pins, where applicable.
- The body size (length × width) is a nominal value and does not include pins.



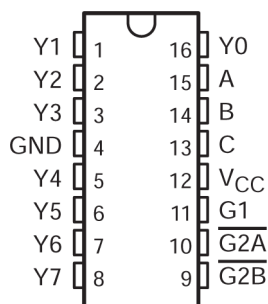
Logic Diagram (Positive Logic)



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## 3 Pin Configuration and Functions



**Figure 3-1. D, N, or PW Package (Top View)**

**Table 3-1. Pin Functions**

PIN		I/O	DESCRIPTION
NAME	NO.		
Y1	1	O	Data output Y1
Y2	2	O	Data output Y2
Y3	3	O	Data output Y3
GND	4	-	Ground
Y4	5	O	Data output Y4
Y5	6	O	Data output Y5
Y6	7	O	Data output Y6
Y7	8	O	Data output Y7
G2B	9	I	Input enable, active low
G2A	10	I	Input enable, active low
G1	11	I	Input enable, active high
VCC	12	-	Supply
C	13	I	Select input C
B	14	I	Select input B
A	15	I	Select input A
Y0	16	O	Data output Y0

**Figure 3-2. Pin Functions**

## 4 Specifications

### 4.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

		MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage range	-0.5	7	V
V <sub>I</sub> <sup>(2)</sup>	Input voltage range	-0.5	V <sub>CC</sub> +0.5	V
V <sub>O</sub> <sup>(2)</sup>	Output voltage range	-0.5	V <sub>CC</sub> +0.5	V
I <sub>IK</sub>	Input clamp current	(V <sub>I</sub> < 0 or V <sub>I</sub> > V <sub>CC</sub> )		±20 mA
I <sub>OK</sub>	Output clamp current	(V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CC</sub> )		±50 mA
I <sub>O</sub>	Continuous output current	(V <sub>O</sub> = 0 or V <sub>CC</sub> )		±50 mA
	Continuous current through V <sub>CC</sub> or GND			±200 mA
T <sub>stg</sub>	Storage temperature range	-65°	150°	C

- (1) Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

### 4.2 Recommended Operating Conditions

		MIN	NOM	MAX	UNIT
V <sub>CC</sub>	Supply voltage	3	5	5.5	V
V <sub>IH</sub>	High-level input voltage	V <sub>CC</sub> = 3 V	2.1		V
		V <sub>CC</sub> = 4.5 V	3.15		
		V <sub>CC</sub> = 5.5 V	3.85		
V <sub>IL</sub>	Low-level input voltage	V <sub>CC</sub> = 3 V		0.9	V
		V <sub>CC</sub> = 4.5 V		1.35	
		V <sub>CC</sub> = 5.5 V		1.65	
V <sub>I</sub>	Input voltage	0		V <sub>CC</sub>	V
V <sub>O</sub>	Output voltage	0		V <sub>CC</sub>	V
I <sub>OH</sub>	High-level output current	V <sub>CC</sub> = 3 V		-4	mA
		V <sub>CC</sub> = 4.5 V		-24	
		V <sub>CC</sub> = 5.5 V		-24	
I <sub>OL</sub>	Low-level output current	V <sub>CC</sub> = 3 V		12	mA
		V <sub>CC</sub> = 4.5 V		24	
		V <sub>CC</sub> = 5.5 V		24	
Δt/Δv	Input transition rise or fall rate	0		10	ns/V
T <sub>A</sub>	Operating free-air temperature	-40		85	°C

## 4.3 Thermal Information

THERMAL METRIC <sup>(1)</sup>		74AC11138			UNIT
		D	N	PW	
		16 PINS	16 PINS	16 PINS	
R <sub>θJA</sub>	Junction-to-ambient thermal resistance	130	110	50	CW

(1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report ([SPRA953](#)).

## 4.4 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	T <sub>A</sub> = 25 °C			MIN	MAX	UNIT
			MIN	TYP	MAX			
V <sub>OH</sub>	I <sub>OH</sub> = –50 μA	3 V	2.9			2.9		V
		4.5 V	4.4			4.4		
		5.5 V	5.4			5.4		
	I <sub>OH</sub> = –4 mA	3 V	2.58			2.48		
		4.5 V	3.94			3.8		
	I <sub>OH</sub> = –24 mA	5.5 V	4.94			4.8		
	I <sub>oh</sub> = –75 mA <sup>(1)</sup>	5.5 V				3.85		
V <sub>OL</sub>	I <sub>OL</sub> = 50 μA	3 V			0.1		0.1	V
		4.5 V			0.1		0.1	
		5.5 V			0.1		0.1	
	I <sub>OL</sub> = 12 mA	3 V			0.36		0.44	
		4.5 V			0.36		0.44	
	I <sub>OL</sub> = 24 mA	5.5 V			0.36		0.44	
	I <sub>OL</sub> = 75 mA <sup>(1)</sup>	5.5 V					1.65	
I <sub>I</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	5.5 V			±0.1		±1	μA
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0	5.5 V			4		40	μA
C <sub>i</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	5 V		3.5				pF

(1) Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

## 4.5 Switching Characteristics, V<sub>CC</sub> = 3.3 V ± 0.3 V

over recommended operating free-air temperature range, V<sub>CC</sub> = 3.3 V ± 0.3 V (unless otherwise noted) (see [Load Circuit and Voltage Waveforms](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T <sub>A</sub> = 25 °C			MIN	MAX	UNIT
			MIN	TYP	MAX			
t <sub>PLH</sub>	A, B, C	Any Y	1.5	8.3	10.2	1.5	11.4	ns
t <sub>PHL</sub>			1.5	8.9	10.9	1.5	12.2	
t <sub>PLH</sub>	G1	Any Y	1.5	7.2	9.2	1.5	10.2	ns
t <sub>PHL</sub>			1.5	7.3	9.4	1.5	10.5	
t <sub>PLH</sub>	G2A, G2B	Any Y	1.5	8.2	10.4	1.5	11.5	ns
t <sub>PHL</sub>			1.5	8.3	10.4	1.5	11.6	

## 4.6 Switching Characteristics, $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$

over recommended operating free-air temperature range,  $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$  (unless otherwise noted) (see [Load Circuit and Voltage Waveforms](#))

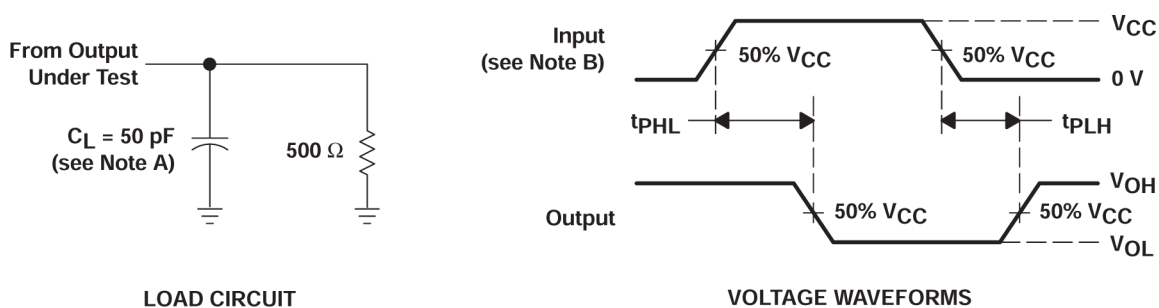
PARAMETER	FROM (INPUT)	TO (OUTPUT)	$T_A = 25^\circ\text{C}$			MIN	MAX	UNIT
			MIN	TYP	MAX			
$t_{PLH}$	A, B, C	Any Y	1.5	5.7	7.3	1.5	8.1	ns
$t_{PHL}$			1.5	6.2	7.9	1.5	8.8	
$t_{PLH}$	G1	Any Y	1.5	5.1	6.9	1.5	7.5	ns
$t_{PHL}$			1.5	5.2	6.9	1.5	7.7	
$t_{PLH}$	$\overline{G2A}, \overline{G2B}$	Any Y	1.5	5.8	7.6	1.5	8.3	ns
$t_{PHL}$			1.5	5.6	7.5	1.5	8.3	

## 4.7 Operating Characteristics

$V_{CC} = 5\text{ V}$ ,  $T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS		TYP	UNIT
$C_{pd}$	Power dissipation capacitance per gate	$C_L = 50\text{ pF}$	$f = 1\text{ MHz}$	51	pF

## 5 Parameter Measurement Information



- A.  $C_L$  includes probe and jig capacitance.
- B. Input pulses are supplied by generators having the following characteristics:  $PRR \leq 1 \text{ MHz}$ ,  $Z_O = 50 \Omega$ ,  $t_r = 3 \text{ ns}$ ,  $t_f = 3 \text{ ns}$ .
- C. The outputs are measured one at a time with one input transition per measurement.

**Figure 5-1. Load Circuit and Voltage Waveforms**

## 6 Detailed Description

### 6.1 Overview

The 74AC11138 circuit is designed to be used in high-performance memory-decoding or data-routing applications requiring very short propagation delay times. In high-performance memory systems, this decoder can be used to minimize the effects of system decoding. When employed with high-speed memories utilizing a fast enable circuit, the delay times of this decoder and the enable time of the memory are usually less than the typical access time of the memory. This means that the effective system delay introduced by the decoder is negligible.

The conditions at the binary-select (A, B, C) inputs and the three enable (G1, G2A, G2B) inputs select one of eight output lines. Two active-low and one active-high enable inputs reduce the need for external gates or inverters when expanding. A 24-line decoder can be implemented without external inverters and a 32-line decoder requires only one inverter. An enable input can be used as a data input for demultiplexing applications.

The 74AC11138 is characterized for operation from  $-40^{\circ}\text{C}$  to  $85^{\circ}\text{C}$ .

### 6.2 Functional Block Diagram

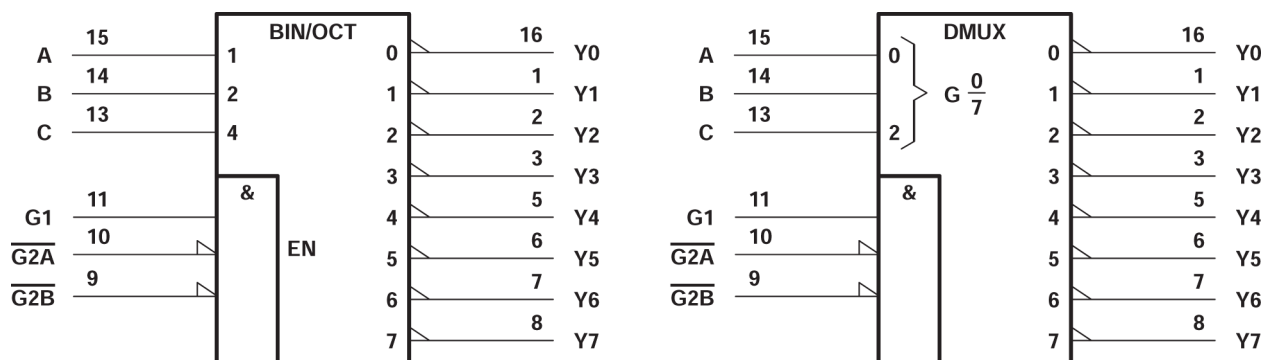
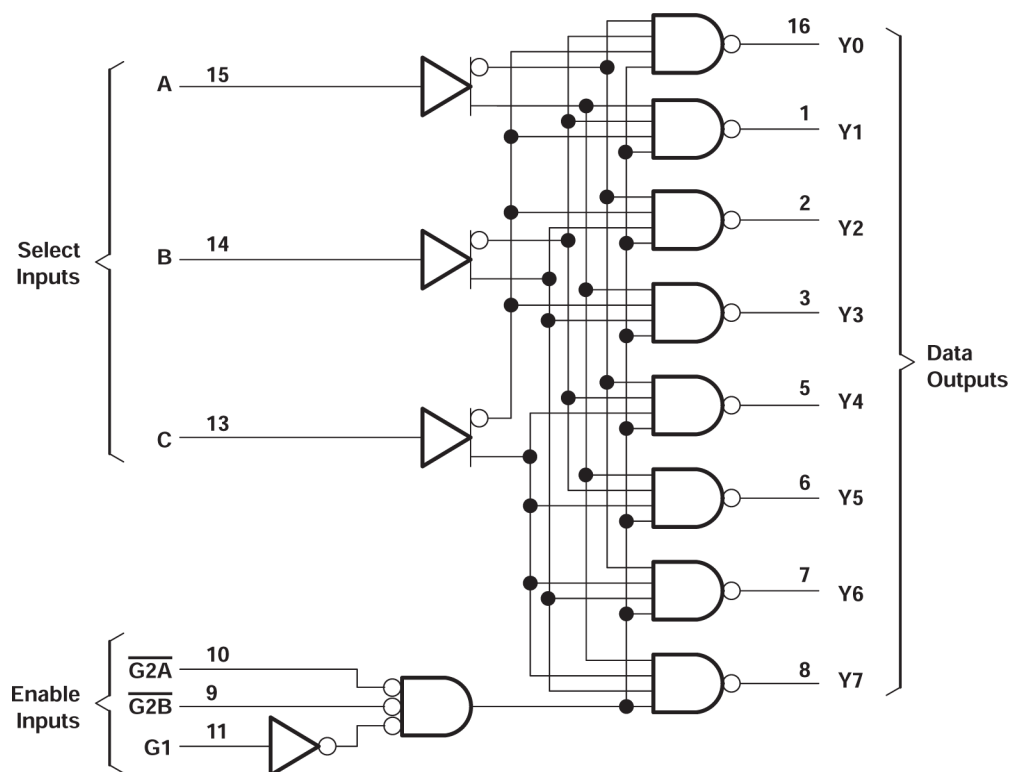


Figure 6-1. Logic Symbols (Alternatives)

†  
†

† These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.





**Figure 6-2. Logic Diagram (Positive Logic)**

## 6.3 Device Functional Modes

Function Table

ENABLE INPUTS			SELECT INPUTS			OUTPUTS							
G1	G2A	G2B	C	B	A	Y0	Y1	Y2	Y3	Y4	Y5	Y6	Y7
X	H	X	X	X	X	H	H	H	H	H	H	H	H
X	X	H	X	X	X	H	H	H	H	H	H	H	H
L	X	X	X	X	X	H	H	H	H	H	H	H	H
H	L	L	L	L	L	L	H	H	H	H	H	H	H
H	L	L	L	L	H	H	L	H	H	H	H	H	H
H	L	L	L	H	L	H	H	L	H	H	H	H	H
H	L	L	L	H	H	H	H	H	L	H	H	H	H
H	L	L	H	L	L	H	H	H	H	L	H	H	H
H	L	L	H	L	H	H	H	H	H	H	L	H	H
H	L	L	H	H	L	H	H	H	H	H	H	L	H
H	L	L	H	H	H	H	H	H	H	H	H	H	L

## 7 Application and Implementation

### Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

### 7.1 Application Information

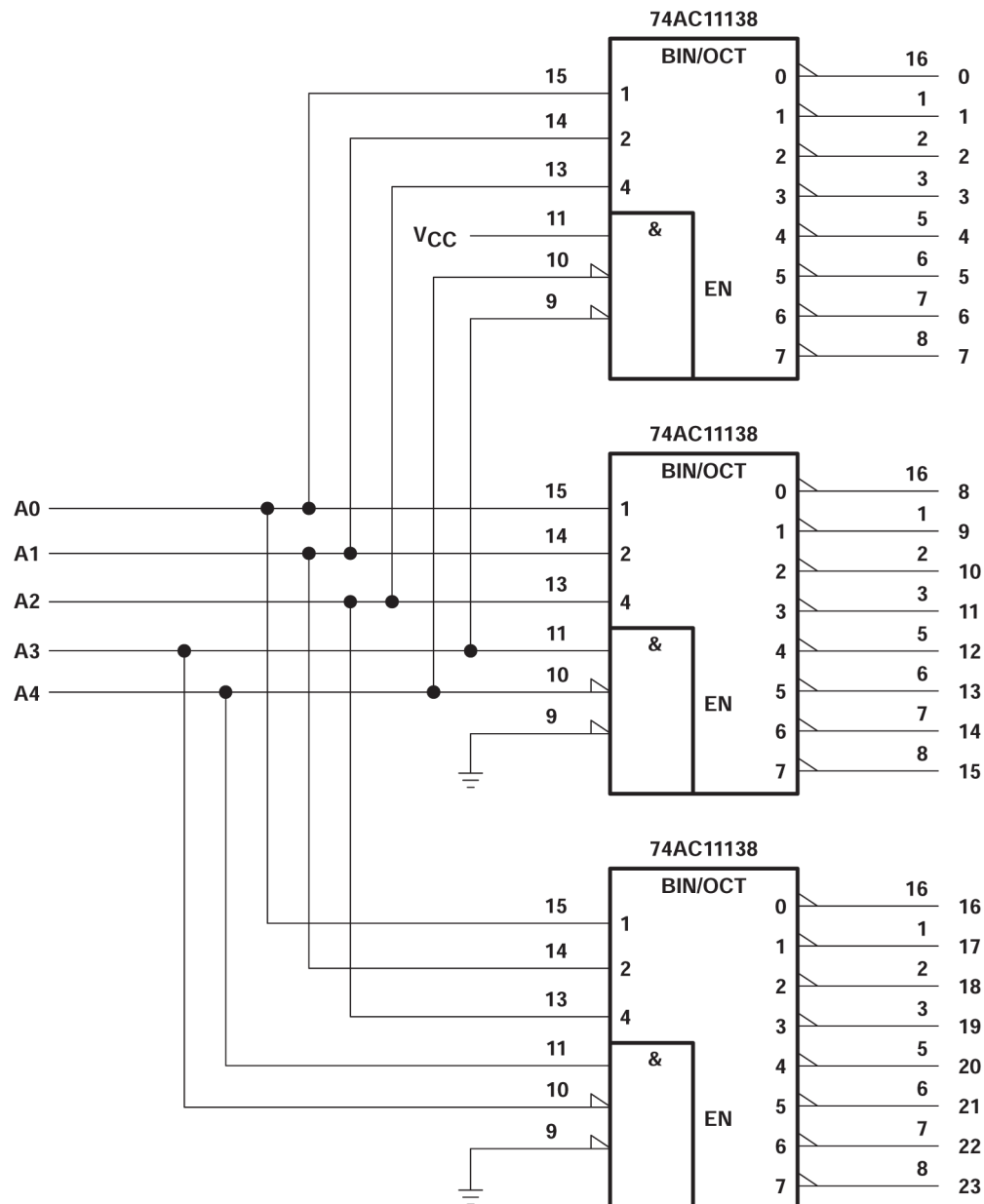
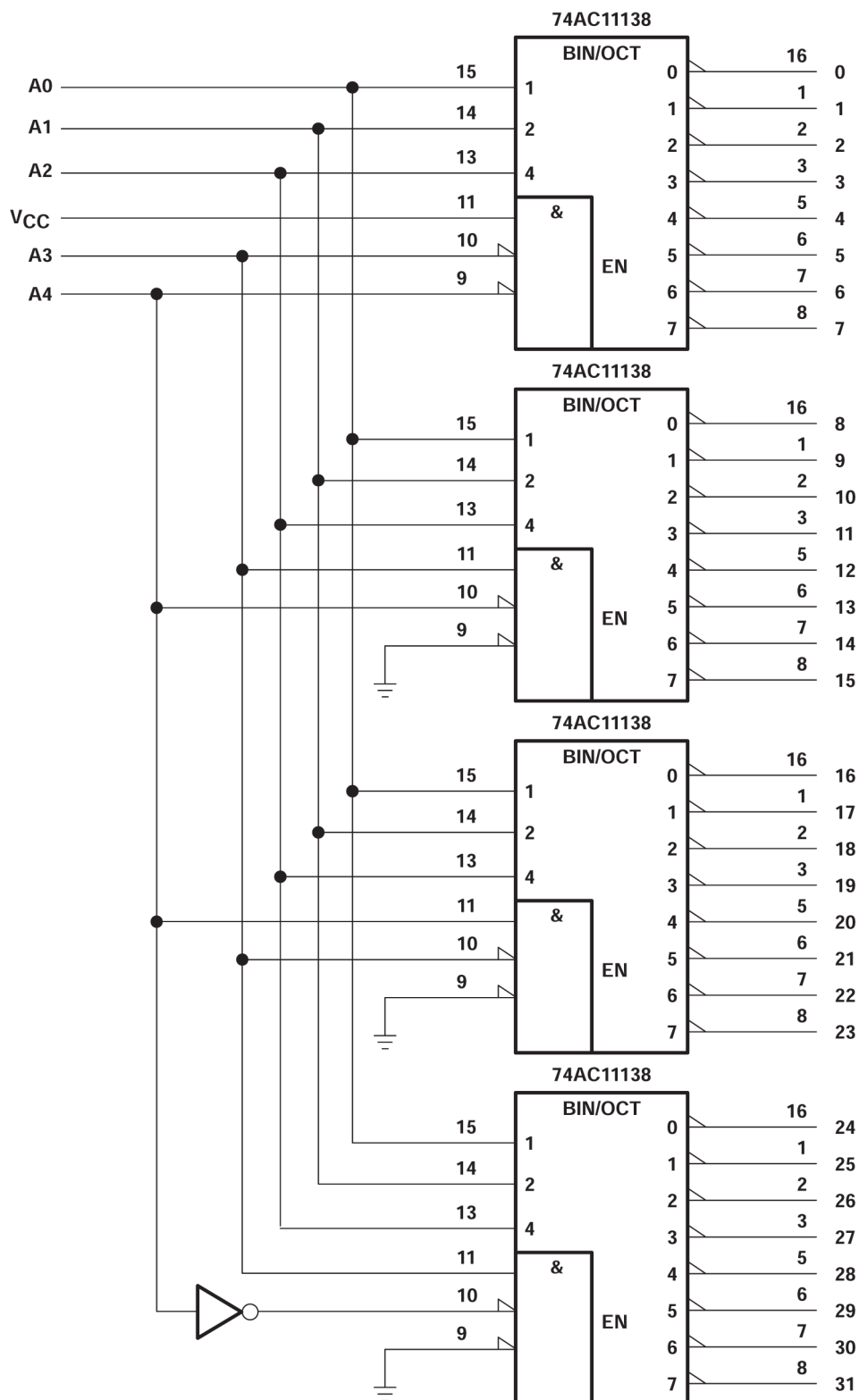


Figure 7-1. 24-Bit Decoding Scheme



**Figure 7-2. 32-Bit Decoding Scheme**

## 7.2 Power Supply Recommendations

The power supply can be any voltage between the minimum and maximum supply voltage rating located in the *Absolute Maximum Ratings* section. Each  $V_{CC}$  terminal must have a good bypass capacitor to prevent power disturbance. For devices with a single supply, TI recommends a 0.1- $\mu$ F capacitor; if there are multiple  $V_{CC}$  terminals, then TI recommends a 0.01- $\mu$ F or 0.022- $\mu$ F capacitor for each power terminal. Multiple bypass capacitors can be paralleled to reject different frequencies of noise. Frequencies of 0.1  $\mu$ F and 1  $\mu$ F are commonly used in parallel. The bypass capacitor must be installed as close as possible to the power terminal for best results.

## 7.3 Layout

### 7.3.1 Layout Guidelines

When using multiple bit logic devices, inputs should not float. In many cases, functions or parts of functions of digital logic devices are unused. Some examples are when only two inputs of a triple-input AND gate are used, or when only 3 of the 4-buffer gates are used. Such unused input pins must not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. All unused inputs of digital logic devices must be connected to a logic high or logic low voltage, as defined by the input voltage specifications, to prevent them from floating. The logic level that must be applied to any particular unused input depends on the function of the device. Generally, the inputs are tied to GND or  $V_{CC}$ , whichever makes more sense for the logic function or is more convenient.

## 8 Device and Documentation Support

TI offers an extensive line of development tools. Tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below.

### 8.1 Documentation Support (Analog)

#### 8.1.1 Related Documentation

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

**Table 8-1. Related Links**

PARTS	PRODUCT FOLDER	SAMPLE & BUY	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY
74AC11138	<a href="#">Click here</a>	<a href="#">Click here</a>	<a href="#">Click here</a>	<a href="#">Click here</a>	<a href="#">Click here</a>

### 8.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on [ti.com](#). Click on *Notifications* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

### 8.3 Support Resources

[TI E2E™ support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

### 8.4 Trademarks

TI E2E™ is a trademark of Texas Instruments.

All trademarks are the property of their respective owners.

### 8.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

### 8.6 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

## 9 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision B (April 1996) to Revision C (May 2024)	Page
• Added <i>Package Information</i> table, <i>Pin Functions</i> table, <i>Thermal Information</i> table, <i>Device Functional Modes</i> , <i>Application and Implementation</i> section, <i>Device and Documentation Support</i> section, and <i>Mechanical, Packaging, and Orderable Information</i> section .....	1

## 10 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

## PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
74AC11138DR	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC11138	<a href="#">Samples</a>
74AC11138N	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-40 to 85	74AC11138N	<a href="#">Samples</a>
74AC11138NSR	ACTIVE	SO	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC11138	<a href="#">Samples</a>
74AC11138PWR	ACTIVE	TSSOP	PW	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AE138	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and

continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



4040047-6/M 06/11





4220204/A 02/2017

## NOTES:

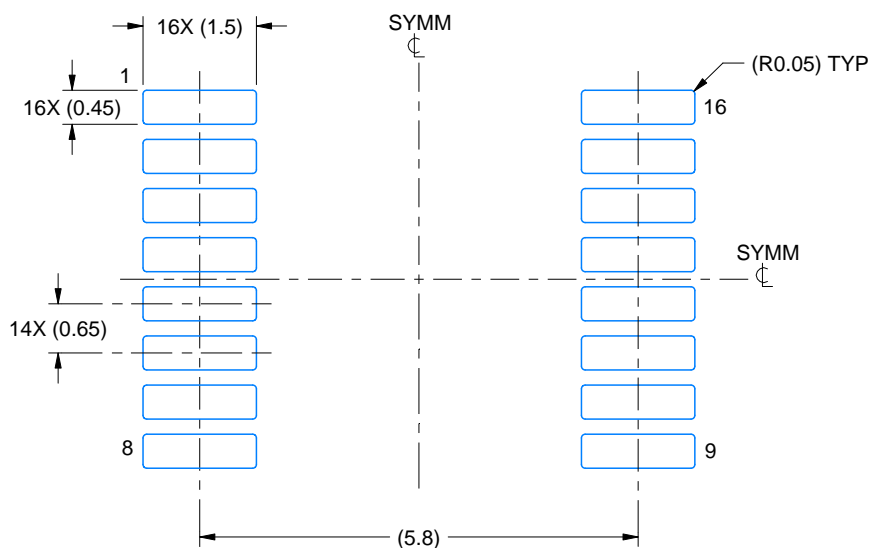
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

# EXAMPLE BOARD LAYOUT

PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 10X



SOLDER MASK DETAILS

4220204/A 02/2017

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

## EXAMPLE STENCIL DESIGN

PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 10X

4220204/A 02/2017

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

## N (R-PDIP-T\*\*)

16 PINS SHOWN

## PLASTIC DUAL-IN-LINE PACKAGE



PINS **	14	16	18	20
DIM				
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



14/18 Pin Only  
20 Pin vendor option

4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - The 20 pin end lead shoulder width is a vendor option, either half or full width.



# PACKAGE OUTLINE

NS0016A

SOP - 2.00 mm max height

SOP



4220735/A 12/2021

## NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.

# EXAMPLE BOARD LAYOUT

NS0016A

SOP - 2.00 mm max height

SOP



SOLDER MASK DETAILS

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NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.

6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

NS0016A

SOP - 2.00 mm max height

SOP



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:7X

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NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.



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